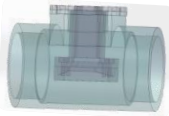
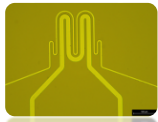


PRODUCTS



MEMS Mass Flow Sensors

Technology: Thin film MEMS
 Flow Range: 0 to 100 LPM
 Operating Temperature: 18 to 50 °C
 Output: Analog/ Digital
 Media: Air/ Oxygen

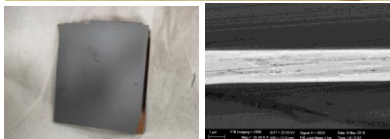
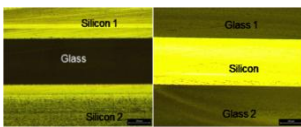


Temperature Sensors

Pt 1000, Thin film RTD
 Temp Range: -25 to 200 °C
 Accuracy: $\pm 0.5^\circ\text{C}$
 Sensitivity: $2.338 \Omega / ^\circ\text{C}$
 Die Size: 2.5 mm x 2.5 mm

TECHNOLOGIES

Wafer Bonding



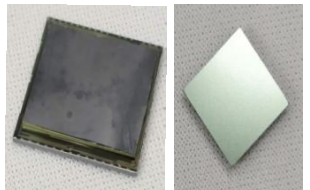
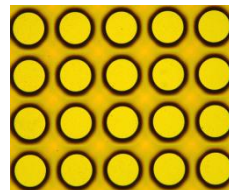
Triple stack bonding

Glass – Silicon – Glass
 Silicon – Glass – Silicon
 Bond Strength: 16.7 MPa

Low temp. Cu-Cu thermo-compression bonding

Bonding at $<300^\circ\text{C}$
 For advanced microsystems packaging

Flip Chip Bonding

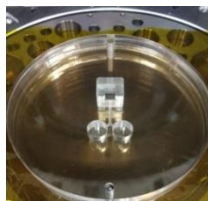
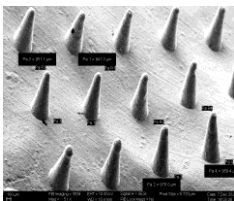


Bump array

Bonded Samples

Thermo compression, reflow, eutectic, epoxy and Thermo sonic bonding
 Temperature up to 450°C
 Force range up to 100 kg
 Fine pitch bonding of $10 \mu\text{m}$

Polymer devices for Bio-Medical



Dissolvable MNA

Solid MNA

Bio Chip

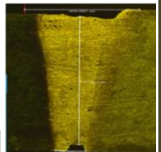
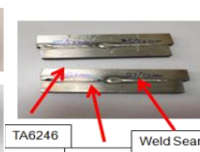
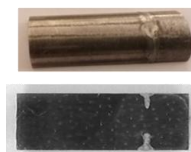
Features

Diameter $200-400 \mu\text{m}$
 Height : $500-700 \mu\text{m}$
 Material: PMMA, Hydrogel

Features

Multilayered stack
 functionalized elements

E-Beam Welding



Inconel 625

TA6246

TA64

Weld Seam

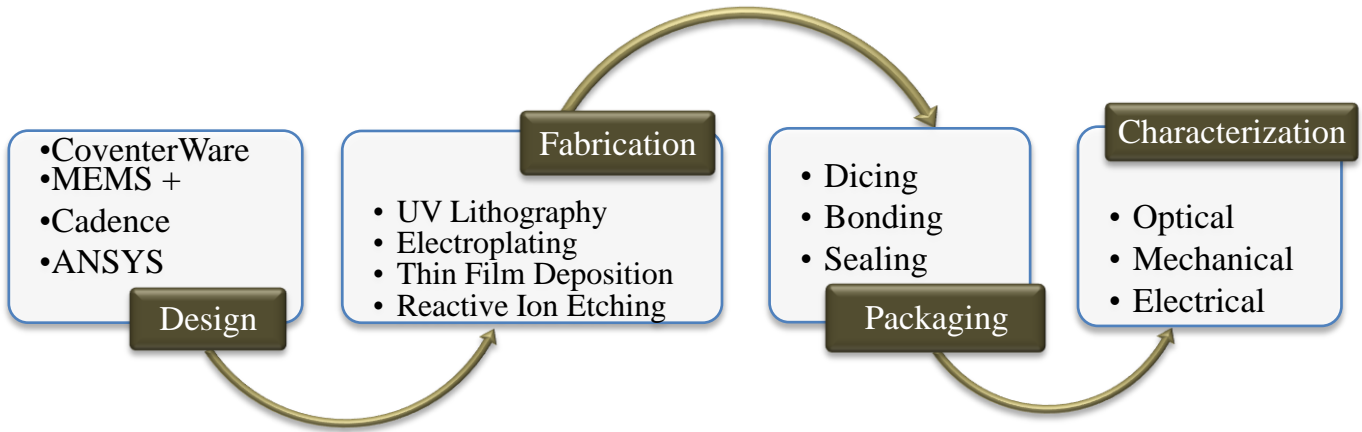
Ti-64 – Ti6246

Welding of rare dissimilar materials

Features

Dissimilar material weld
 Fine weld bead

FACILITIES



UV NIL



HOT EMBOSsing



MASK ALIGNER



WAFER DICER



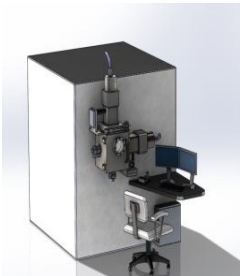
FLIP CHIP BONDER



WIRE
BONDER



BOND
TESTER



E- BEAM
WELDING



SEAM
SEALER



WAFER
BONDER



WAFER BONDER



MASK WRITER



ELECTROPLATING



WET BENCHES

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